

98426-YXX-XX-XXXLF

**PLATING**

- G : 0.76 GXT / 2µm MIN TIN ON TAIL
- S : 0.38 GXT / 2µm MIN TIN ON TAIL
- F : GOLD FLASH /2µm MIN TIN ON TAIL
- T : 2µm MIN FULL TIN

UNDERPLATING 1.27µm NICKEL MIN.

LEAD FREE AND RoHS COMPATIBLE, NOTE 6

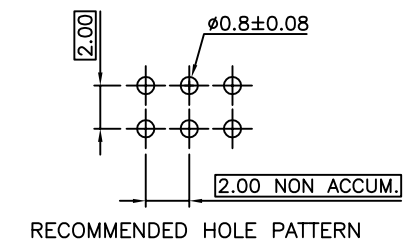
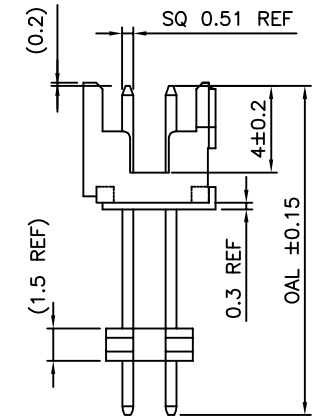
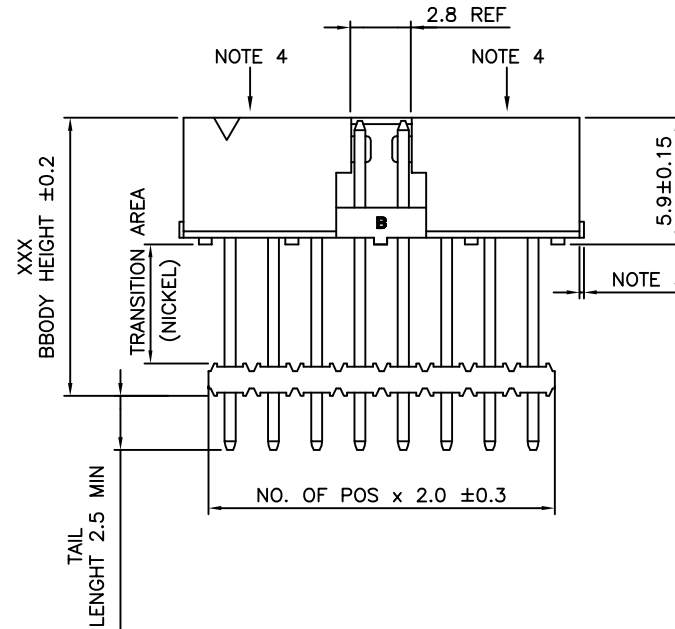
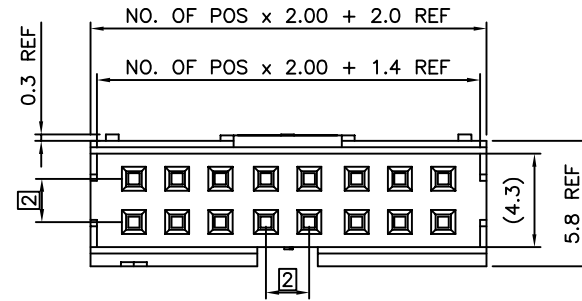
STACK HEIGHT : XXX  
 - MIN= 104 (10.4MM)  
 - MAX= 290 (29.0MM)

NO. OF POS PER ROW, 03 TO 25

PIN STYLE	OAL
01	12.8
02	13.5
03	14.1
04	15.6
05	16.3
06	17.1
07	18.3
08	19.1
09	20.3
10	21.1
11	22.3
12	23.3
13	26.0
14	28.0
15	30.0
16	32.0

**NOTES:**

- 1 - MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC UL 94V-0, COLOR CREAM (SHROUD) AND BLACK(UNSHROUDED)
- 2 - MATERIAL TERMINAL: COPPER ALLOY
- 3 - BLIBOX PACKAGING
- 4 - SHROUDED RETENTION FORCE 3N MIN PER POSITION
- 5 - 0.3 MAX PROTRUSION FOR -03 TO 11
- 6 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS
  - a - PLATING:
    - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
  - b - MANUFACTURING PROCESS COMPATIBILITY
    - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
  - c - LABELING:
    - MEETS PACKAGING SPECS AS PER GS-14-920
  - d - LEGAL STATEMENT: SEE GS-22-008
- 6 - THIS PRODUCT IS NOT INTENDED TO BE USED THROUGH REFLOW PROCESS



mat'l. code		surface		tolerance		projection		product family	
		ISO 1302		ISO 406		ISO 101		MINITEK	
ltr		ecn no		date		tolerances unless otherwise specified		title	
A		F09-0227		JCO 09.12.07		X.X ±0.3		SHR STACKING	
B		F10-0067		JCO 10.06.29		X.XX ±0.13		HEADER MINITEK	
						X.XXX ±0.05		scale 1:1	
		dr		L.MULIN		09.04.02		dwg no	
		engr		J.COMPAGNON		09.04.02		sheet 1 of 1	
		chr		JCO		09.12.07		size	
		app		J.CO		09.12.07		A3	
sheet index		revision sheet						type	
								CUSTOMER Drawing	

PDM: Rev:B

STATUS: Released

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